Abstract

[Problem]

To provide a technique capable of reducing an effort required for setting bond coordinates.

[Solution]

A die bonding device includes a display device displaying a bond coordinate setting screen that has: a first display window displaying an image of a substrate; a second display window displaying images of a plurality of dice; a third display window capable of inputting and outputting bond coordinates of a base die bonded to a surface of the substrate; and a fourth display window capable of inputting and outputting bond coordinates of a die bonded offset to the base die.

[Selected Drawing]Fig. 7